**MARKING** 



# TinyLogic UHS Dual Buffer (Open-Drain Outputs)

### NC7WZ07

#### **Description**

The NC7WZ07 is a dual buffer with open–drain outputs from **onsemi**'s Ultra–High Speed (UHS) series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra–high speed with high output drive, while maintaining low static power dissipation over a broad  $V_{CC}$  operating range. The device is specified to operate over a very broad  $V_{CC}$  operating range. The device is specified to operate over the 1.65 V to 5.5 V  $V_{CC}$  range. The inputs and outputs are high impedance when  $V_{CC}$  is 0 V. Inputs tolerate voltages up to 5.5 V independent of  $V_{CC}$  operating voltage.

#### **Features**

- Ultra-High Speed: t<sub>PZL</sub> = 2.3 ns (Typical)
- High I<sub>OL</sub> Output Drive: ±24 mA at 3 V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range: 1.65 V to 5.50 V
- Power Down High-Impedance Inputs / Outputs
- Over-Voltage Tolerance Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise / EMI Reduction Circuitry
- Ultra-Small MicroPak<sup>TM</sup> Packages
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

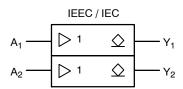
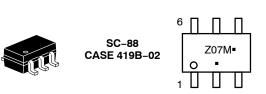


Figure 1. Logic Symbol

# SIP6 CASE 127EB Pin 1 UDFN6 CASE 517DP D3KK XYZ D3KK XYZ



D3, Z07 = Specific Device Code

KK = 2-Digit Lot Run Traceability Code
 XY = 2-Digit Date Code Format
 Z = Assembly Plant Code

M = Date Code\*
= Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or position may vary depending upon manufacturing location.

#### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

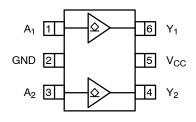


Figure 2. SC-88 (Top View)

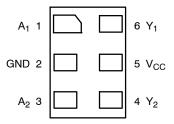
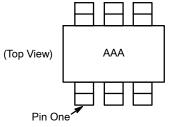


Figure 3. MicroPak (Top Through View)



#### NOTES:

- AAA represents product code top mark (see Ordering Information).
   Orientation of top mark determines pin one location.
   Read the top mark left to right, pin one is the lower left pin.

Figure 4. Pin 1 Orientation

#### **PIN DEFINITIONS**

Pin # SC-88	Pin # MicroPak	Name	Description
1	1	A <sub>1</sub>	Input
2	2	GND	Ground
3	3	A <sub>2</sub>	Input
4	4	Y <sub>2</sub>	Output
5	5	V <sub>CC</sub>	Supply Voltage
6	6	Y <sub>1</sub>	Output

#### **FUNCTION TABLE** (Y = A)

Inputs	Output		
A	Υ		
LOW Logic Level	LOW Logic Level		
HIGH Logic Level	HIGH Impedance Output State, Open Drain		

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	Supply Voltage	-0.5	6.5	V	
V <sub>IN</sub>	DC Input Voltage		-0.5	6.5	V
V <sub>OUT</sub>	DC Output Voltage		-0.5	6.5	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < 0 V	-	-50	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < 0 V	-	-50	mA
I <sub>OUT</sub>	DC Output Current		=	±50	mA
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current	=	±100	mA	
T <sub>STG</sub>	Storage Temperature Range	-65	+150	°C	
TJ	Junction Temperature Under Bias		=	+150	°C
TL	Junction Lead Temperature (Soldering	g, 10 Seconds)	=	+260	°C
P <sub>D</sub>	Power Dissipation in Still Air	SC-88	=	332	mW
		MicroPak-6	=	812	1
		MicroPak2™-6	-	812	1
ESD	Human Body Model, JEDEC: JESD22-A114		-	4000	V
	Charge Device Model, JEDEC: JESD2	22-C101	-	2000	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Retention		1.5	5.5	
V <sub>IN</sub>	Input Voltage		0	5.5	V
V <sub>OUT</sub>	Output Voltage		0	5.5	V
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Times	V <sub>CC</sub> at 1.8 V ±0.15 V, 2.5 V ±0.2 V	0	20	ns/V
		V <sub>CC</sub> at 3.3 V ±0.3 V	0	10	
		V <sub>CC</sub> at 5.0 V ±0.5 V	0	5	
T <sub>A</sub>	Operating Temperature		-40	+85	°C
$\theta_{\sf JA}$	Thermal Resistance	SC-88-6	-	377	°C/W
		MicroPak-6	-	154	
		MicroPak2-6	-	154	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

4. Unused inputs must be held HIGH or LOW. They may not float.

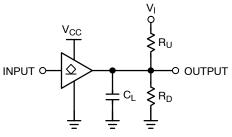
#### DC ELECTICAL CHARACTERISTICS

				T,	<sub>Δ</sub> = +25°	С	T <sub>A</sub> = -40	to +85°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min	Тур	Max	Min	Max	Unit
$V_{IH}$	HIGH Level Input Voltage	1.65 to 1.95		0.65 V <sub>CC</sub>	-	-	0.65 V <sub>CC</sub>	-	V
		2.30 to 5.50		0.70 V <sub>CC</sub>	-	-	0.70 V <sub>CC</sub>	-	1
$V_{IL}$	LOW Level Input Voltage	1.65 to 1.95		-	-	0.35 V <sub>CC</sub>	-	0.35 V <sub>CC</sub>	V
		2.30 to 5.50		-	-	0.30 V <sub>CC</sub>	-	0.30 V <sub>CC</sub>	1
I <sub>LKG</sub>	HIGH Level Output Leakage Current	1.65 to 5.50	$V_{IN} = V_{IH}$ or $V_{IL}$ , $V_{OUT} = V_{CC}$ or GND	-	-	±5	-	±10	μΑ
V <sub>OL</sub>	LOW Level Output Voltage	1.65	$V_{IN} = V_{IH} \text{ or } V_{IL},$	_	0.00	0.10	-	0.00	V
		1.80	- I <sub>OL</sub> = 100 μA	-	0.00	0.10	-	0.10	
		2.30		-	0.00	0.10	-	0.10	
		3.00		_	0.00	0.10	-	0.10	1
		4.50		_	0.00	0.10	-	0.10	1
		1.65	I <sub>OL</sub> = 4 mA	-	0.80	0.24	-	0.24	1
		2.30	I <sub>OL</sub> = 8 mA	-	0.10	0.30	-	0.30	
		3.00	I <sub>OL</sub> = 16 mA	-	0.16	0.40	-	0.40	
		3.00	I <sub>OL</sub> = 24 mA	-	0.24	0.55	-	0.55	
		4.50	I <sub>OL</sub> = 32 mA	_	0.25	0.55	-	0.55	
I <sub>IN</sub>	Input Leakage Current	1.65 to 5.5	$0 \leq V_{IN} \leq 5.5 \ V$	-	_	±0.1	-	±1.0	μА
I <sub>OFF</sub>	Power Off Leakage Current	0	V <sub>IN</sub> or V <sub>OUT</sub> = 5.5 V	-	-	1	-	10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	1.65 to 5.50	V <sub>IN</sub> = 5.5 V, GND	_	-	1	-	10	μΑ

#### **AC ELECTRICAL CHARACTERISTICS**

				-	Γ <sub>A</sub> = +25°0	•	T <sub>A</sub> = -40	to +85°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t <sub>PZL</sub>	Propagation Delay	1.65	C <sub>L</sub> = 50 pF,	-	6.6	11.5	-	12.6	ns
	(Figure 5, 6)	1.80	RU = 500 $\Omega$ , RD = 500 $\Omega$ ,	_	5.5	9.5	-	10.5	
		2.50 ±0.20	$V_I = 2 \times V_{CC}$	_	3.7	5.8	-	6.4	
		3.30 ±0.30		_	2.9	4.4	-	4.8	
		5.00 ±0.50		_	2.3	3.5	-	3.9	
t <sub>PLZ</sub>		1.65	$\begin{aligned} C_L &= 50 \text{ pF,} \\ RU &= 500 \ \Omega, \\ RD &= 500 \ \Omega, \\ V_I &= 2 \ x \ V_{CC} \end{aligned}$	-	5.5	11.5	-	12.6	
		1.80		_	4.3	9.5	-	10.5	
		2.50 ±0.20		_	2.8	5.8	-	6.4	
		3.30 ±0.30		_	2.1	4.4	-	4.8	
		5.00 ±0.50		_	1.4	3.5	-	3.9	
C <sub>IN</sub>	Input Capacitance	0		-	2.5	-	-	-	pF
C <sub>OUT</sub>	Output Capacitance	0		-	4.0	-	-	-	pF
C <sub>PD</sub>	Power Dissipation Capacitance	3.30		-	3	-	-	-	pF
	(Note 5) (Figure 7)	5.00	]	_	4	_	-	_	

<sup>5.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle. C<sub>PD</sub> is related to I<sub>CCD</sub> dynamic operating current by the expression: I<sub>CCD</sub> = (C<sub>PD</sub>) (V<sub>CC</sub>) (f<sub>IN</sub>) + (I<sub>CC</sub>static).



#### NOTE:

- 6.  $C_L$  includes load and stray capacitance. 7. Input PRR = 1.0 MHz,  $t_W$  = 500 ns.

Figure 5. AC Test Circuit

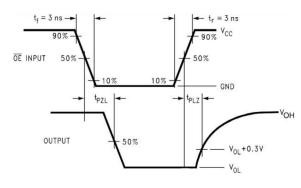
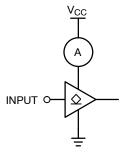


Figure 6. AC Waveforms



#### NOTE:

8. Input = AC Waveform;  $t_r = t_f = 1.8 \text{ ns}$ ; PRR = Variable; Duty Cycle = 50%.

Figure 7. I<sub>CCD</sub> Test Circuit

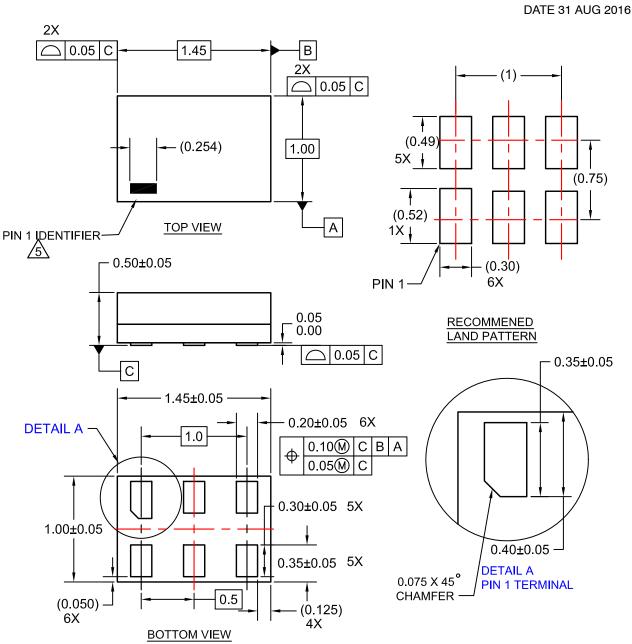
#### **ORDERING INFORMATION**

Part Number	Top Mark	Package	Shipping <sup>†</sup>
NC7WZ07P6X	Z07	SC-88	3000 / Tape & Reel
NC7WZ07P6X-L22347	Z07	SC-88	3000 / Tape & Reel
NC7WZ07L6X	D3	MicroPak	5000 / Tape & Reel
NC7WZ07L6X-L22175	D3	MicroPak	5000 / Tape & Reel
NC7WZ07FHX	D3	MicroPak2	5000 / Tape & Reel
NC7WZ07FHX-L22175	D3	MicroPak2	5000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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NOTES:

- 1. CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-2009
- 4.PIN ONE IDENTIFIER IS 2X LENGTH OF ANY
  - OTHER LINE IN THE MARK CODE LAYOUT.

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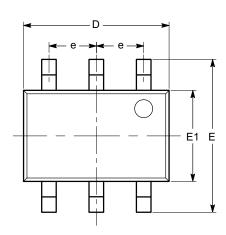
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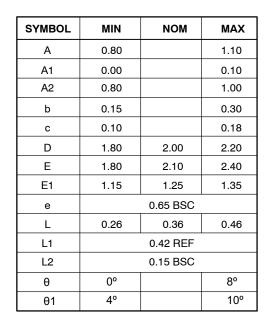


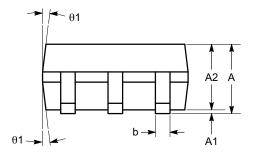
#### SC-88 (SC-70 6 Lead), 1.25x2 CASE 419AD **ISSUE A**

**DATE 07 JUL 2010** 

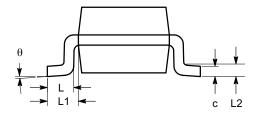


**TOP VIEW** 





SIDE VIEW



**END VIEW** 

#### Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-203.

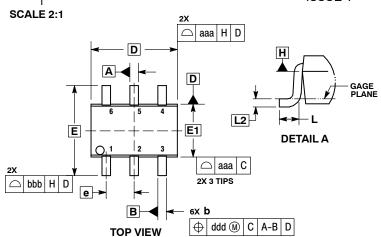
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DESCRIPTION:	SC-88 (SC-70 6 LEAD), 1.	25X2	PAGE 1 OF 1			

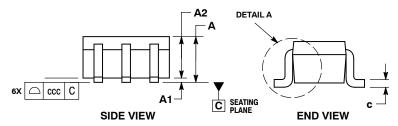
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#### SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE Y**

**DATE 11 DEC 2012** 





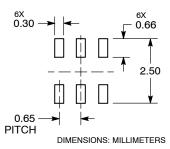
#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M. 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
  DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H. DIMENSIONS b AND B ARE DETERMINED AT DATUM H. DIMENSIONS b AND C APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.

- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

	MILLIMETERS				INCHES	3	
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α			1.10			0.043	
A1	0.00		0.10	0.000		0.004	
A2	0.70	0.90	1.00	0.027	0.035	0.039	
b	0.15	0.20	0.25	0.006	0.008	0.010	
С	0.08	0.15	0.22	0.003	0.006	0.009	
D	1.80	2.00	2.20	0.070	0.078	0.086	
Е	2.00	2.10	2.20	0.078	0.082	0.086	
E1	1.15	1.25	1.35	0.045	0.049	0.053	
е		0.65 BS	С	0.026 BSC			
L	0.26	0.36	0.46	0.010	0.014	0.018	
L2	0.15 BSC 0.15			0.006 BSC			
aaa				0.006			
bbb		0.30		0.012			
ccc	0.10			0.004			
ddd		0.10		0.004			

## **RECOMMENDED**



**SOLDERING FOOTPRINT\*** 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Date Code\* = Pb-Free Package

(Note: Microdot may be in either location)

- \*Date Code orientation and/or position may vary depending upon manufacturing location.
- \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

#### **STYLES ON PAGE 2**

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#### SC-88/SC70-6/SOT-363 CASE 419B-02 ISSUE Y

**DATE 11 DEC 2012** 

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	STYLE 8: CANCELLED	STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
STYLE 13: PIN 1. ANODE 2. N/C 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 14: PIN 1. VREF 2. GND 3. GND 4. IOUT 5. VEN 6. VCC	STYLE 15: PIN 1. ANODE 1 2. ANODE 2 3. ANODE 3 4. CATHODE 3 5. CATHODE 2 6. CATHODE 1	STYLE 16: PIN 1. BASE 1 2. EMITTER 2 3. COLLECTOR 2 4. BASE 2 5. EMITTER 1 6. COLLECTOR 1	STYLE 17: PIN 1. BASE 1 2. EMITTER 1 3. COLLECTOR 2 4. BASE 2 5. EMITTER 2 6. COLLECTOR 1	STYLE 18: PIN 1. VIN1 2. VCC 3. VOUT2 4. VIN2 5. GND 6. VOUT1
STYLE 19: PIN 1. I OUT 2. GND 3. GND 4. V CC 5. V EN 6. V REF	STYLE 20: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR	STYLE 21: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. N/C 6. CATHODE 1	STYLE 22: PIN 1. D1 (i) 2. GND 3. D2 (i) 4. D2 (c) 5. VBUS 6. D1 (c)	STYLE 23: PIN 1. Vn 2. CH1 3. Vp 4. N/C 5. CH2 6. N/C	STYLE 24: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
STYLE 25: PIN 1. BASE 1 2. CATHODE 3. COLLECTOR 2 4. BASE 2 5. EMITTER 6. COLLECTOR 1	STYLE 26: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1	STYLE 27: PIN 1. BASE 2 2. BASE 1 3. COLLECTOR 1 4. EMITTER 1 5. EMITTER 2 6. COLLECTOR 2	STYLE 28: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN	STYLE 29: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE/ANODE 6. CATHODE	STYLE 30: PIN 1. SOURCE 1 2. DRAIN 2 3. DRAIN 2 4. SOURCE 2 5. GATE 1 6. DRAIN 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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#### UDFN6 1.0X1.0, 0.35P CASE 517DP ISSUE O **DATE 31 AUG 2016** 0.89 0.05 C В 1.00±0.050 Α 2X 5X 0.40 PIN 1 MIN 250uM 0.66 1 00±0 050 1X 0.45 0.05 C **TOP VIEW** 6X 0.19 2X RECOMMENDED LAND PATTERN FOR SPACE CONSTRAINED PCB 0.05 C - 0.90 -0.50±0.05 5X 0.52 SIDE VIEW 6X 0.14±0.05 (0.08)4X -0.73 **DETAIL A** 3 1X 0.57 - 0.20 6X ALTERNATIVE LAND PATTERN FOR UNIVERSAL APPLICATION (0.05)6X5X 0.30±0.05 0.60 0.10M|C|B|A(0.08).05 C 4X 0.35±0.050 **BOTTOM VIEW** NOTES: A. COMPLIES TO JEDEC MO-252 STANDARD B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009

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DESCRIPTION:	UDFN6 1.0X1.0, 0.35P		PAGE 1 OF 1

0.075X45°

**CHAMFER** 

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**DETAIL A** 

PIN 1 LEAD SCALE: 2X

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